Special Issue

Flexible Materials and Stretchable Microdevices

Message from the Guest Editors

The rapid development of flexible materials and stretchable devices has transformed the landscape of microdevice technology, enabling groundbreaking applications in microfluidics, wearable electronics, soft robotics, biomedical sensors, and energy harvesting. These advancements are driving innovation in next-generation micro- and nano-scale devices, offering enhanced adaptability, durability, and multifunctionality. This Special Issue aims to showcase cutting-edge research in the design, fabrication, characterization, and application of flexible and stretchable microdevices. We welcome contributions on novel materials, advanced fabrication techniques, innovative microfabrication strategies, and emerging applications. By bringing together the latest developments in this field, this Special Issue will provide valuable insights into the challenges and opportunities of this exciting research field. In this Special Issue, original research articles and reviews are welcome. We look forward to your contributions!

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